

Docket No. 58102-DIV (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang CONF. NO.: 5161

U.S. SERIAL NO.: 10/787,269 EXAMINER: P. Cao

FILED: February 25, 2004 GROUP: 2814

FOR: SEMICONDUCTOR PACKAGE WITH HEAT DISSIPATING
STRUCTURE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicant is in receipt of the Office Action dated June 19, 2007 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.